



---

**UPDATE CHANGE NOTIFICATION # 16346**

Generic Copy

---

**Issue Date: 18-Aug-2010**

**TITLE:** Solder Die Attach for the SOT223 Package

**PROPOSED FIRST SHIP DATE:** 18-Aug-2010

**AFFECTED CHANGE CATEGORY(S):** Die Attach Assembly

**ADDITIONAL RELIABILITY DATA:** N/A

**SAMPLES:** Contact your local ON Semiconductor Sales Office

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or Gerry Walcott  
< [g.walcott@onsemi.com](mailto:g.walcott@onsemi.com) >

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.

**DESCRIPTION AND PURPOSE:**

This is a notification that the previously issued Final Product Change Notice #16346 for using a soft solder die attach material for the SOT223 package is not applicable to the part numbers listed incorrectly below in this document.



**UPDATE CHANGE NOTIFICATION #16346**

**List of affected General Parts:**

NIF5002NT1  
NIF5002NT1G  
NIF5002NT3  
NIF5002NT3G  
NIF5003NT1G  
NIF5003NT3G  
NIF625143T1G  
NIF625143T3G  
NIF9N05CLT1  
NIF9N05CLTIG